

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 14. (Cancelled)

15. (Currently Amended) A method of manufacturing a circuit board, the circuit board including a substrate and the substrate including an output side terminal comprising:

a step of mounting a first component within a first region on ~~[[a]]~~ the substrate by a solder connection;

a step of arranging an anisotropic conductive film within a band region of a ~~surface~~ of the substrate;

a step of arranging a second component on the anisotropic conductive film; and

a step of thermocompression-bonding the second component to within a second region on said the substrate with said anisotropic conductive film held therebetween;

wherein said step of arranging said anisotropic conductive film within said band region of said the substrate is performed after said step of mounting the first component on said the substrate by the solder connection;

said step of thermocompression-bonding is performed with a compression bonding head; and

the band region is wider than the head[[.]], the band region extending from the second region toward the output side terminal along a longitudinal direction of a pressing surface of the head.

16. (Previously Presented) A method of manufacturing a circuit board according to claim 15, wherein said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.

17. – 20. (Cancelled)

21. (Currently Amended) A method of manufacturing a circuit board in which components are mounted thereto, the circuit board including an output side terminal disposed along an edge of the circuit board, comprising:

- a.) selecting a band region on a surface of the circuit board;
- b.) soldering a first component onto the circuit board in a first region located outside of the band region; and
- c.) after step b.), mounting a second component on the ~~substrate~~ circuit board within a second region located within the band region with an anisotropic conductive film,

wherein step c.) includes a step of thermocompression-bonding the second component to ~~said substrate~~ the circuit board with a compression bonding head; and

the band region is wider than the head, and

the band region extends from the second region toward the output side terminal along a longitudinal direction of a pressing surface of the head.

22. (Previously Presented) The method of claim 21 where step c.) is performed with a heated compression bonding head, and

wherein the band region is selected to correspond generally to the areas over which the head travels during step c.) thereby preventing impact of the head with the first component and isolating the first component from the heat generated by the head.

23. (Previously Presented) The method of claim 15, wherein the first component is selected from the group of passive and mechanical components, and the second component comprises a semiconductor device.

24. (Cancelled)

25. (Previously Presented) The method of claim 15, wherein alignment marks are provided outside the band region.

26. (Previously Presented) The method of claim 15, wherein the bonding region is selected by performing a solder reflow process.

27. (Previously Presented) The method of claim 15, wherein the band region divides a first set of first components on one part of the substrate and a second set of first components on a second part of the substrate.

28. (Previously Presented) The method of claim 23, wherein the second component is selected from the group of a power source IC and a power source LSI.

29. (Previously Presented) The method of claim 15, wherein the band region extends from one end of the substrate to another end of the substrate.

30. (Previously Presented) The method of claim 15, wherein the band region extends rectilinearly along the substrate.

31. (Previously Presented) The method of claim 15, further comprising:
forming wiring patterns on the substrate in the band region.

32. (Previously Presented) The method of claim 15, further comprising:
forming a dummy electrode at a position associated with the second component.

33. (Cancelled)

34. (Cancelled)

35. (Currently Amended) A method of manufacturing a display device including a display panel and a circuit board, the display panel including a first substrate and a second substrate, the first substrate including an external connection terminal and the second substrate including an output side terminal being connected to the external connection terminal, comprising:

a step of mounting a plurality of first components within first regions on ~~a surface of a~~ the second substrate by a solder connection;

a step of arranging an anisotropic conductive film on a predetermined position of the second substrate;

a step of arranging a second component on the anisotropic conductive film; and

a step of thermocompression-bonding the second component ~~to~~ within a second region on said the second substrate with said anisotropic conductive film held therebetween with a compression bonding head;

wherein said step of arranging said anisotropic conductive film on the predetermined position of ~~said~~ the second substrate is performed after said step of mounting the first components on ~~said the second~~ substrate by the solder connection;

the second substrate includes a band region that extends from the second region toward the output side terminal between the first regions; and

the first substrate of the display panel includes a driving IC~~the band region includes the second component other than the first component, the band region extending along a longitudinal direction of a pressing surface of the compression bonding head.~~

36. (new) The method according to claim 15, further comprising mounting another first component in another first region, the first region and the another first region disposed on opposing sides of the band region such that the band region extends between the first regions toward the output side terminal.

37. (new) The method according to claim 21, wherein the band region is narrower than a surface of the circuit board.

38. (new) The method according to claim 37, further comprising mounting another first component in another first region located outside of the band region, the another first region being disposed on the surface of the circuit board on a side of circuit board that opposes the first region.

39. (new) The method according to claim 35, wherein the band region is disposed between the first regions, and the band region is narrower than a surface of the second substrate.